# **Dynamic Vision Sensor**

The Road to Market

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#### The Road Less Traveled



image by aosleading

# **Market Driven Requirements VS Early DVS Prototypes**

Requirements	Early DVS Prototypes
Low Cost	Large Pixel No standard for Quality / Die sorting
Minimal Module Size	Large, due to large Pixel -> Large optical format
Ultra Low Power	Low power
Good Event Quality	Redundant events (especially at low light) Motion artifacts, Timing accuracy Noise, Flicker
Low Data Rate	Scene dependent; In some cases may exceed CIS typical throughput
Vision processing at Edge	Not available

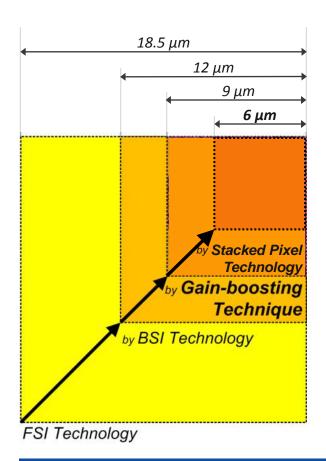
#### The Road to Market - Overview

- Reducing Cost and Module Size
- Reducing Power
- Delivering Good Event Quality
- Data Throughput Reduction
- Event Processing Acceleration
- Summary

#### The Road to Market - Overview

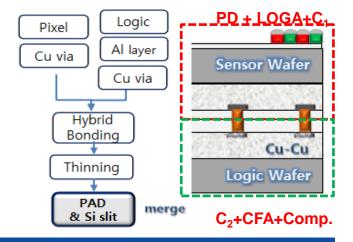
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#### **Reducing Pixel Size and Optical format**



#### **Pixel Shrink**

- BSI process
- Downsizing MIMCAP
   Without a decrease in minimum contrast sensitivity
- Stacked Cu-Cu Technology



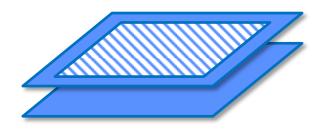
18.5 x 18.5  $\mu$ m<sup>2</sup>  $\rightarrow$  6 x 6  $\mu$ m2 ~90% pixel area reduction

## **Reducing Pixel Size and Optical format**

o Photo Enhancement:



**3μm x 3μm Photodiode** / 9μm x 9μm Pixel



**5μm x 5μm Photodiode** / 6 μm x 6 μm Pixel / Wafer-stacking

#### **Delivering Product to Market - Overview**

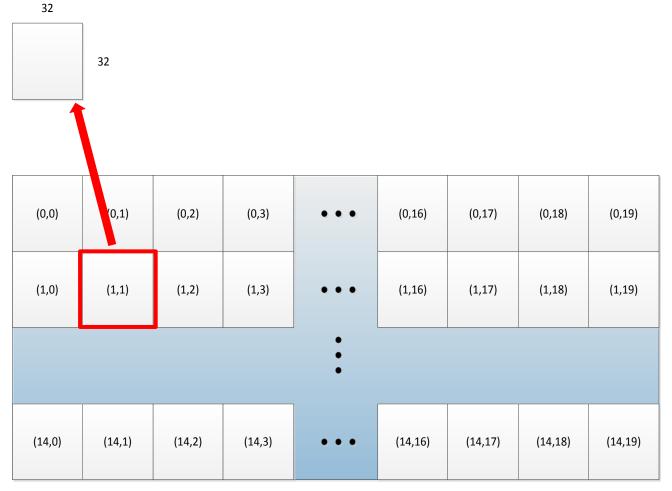
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## **Reducing Power**

- Use Samsung's advanced process
- Subsampling modes
- Dynamic wakeup, window of interest

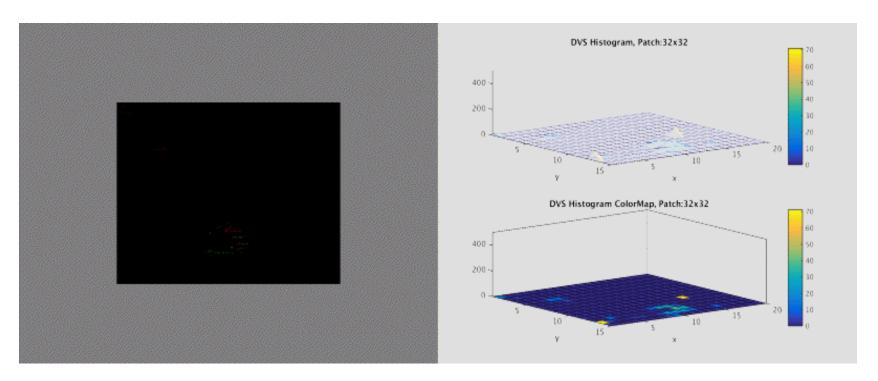
## **Reducing Power: Statistics for Dynamic Decisions**

Spatial Histogram & Blocking Area:



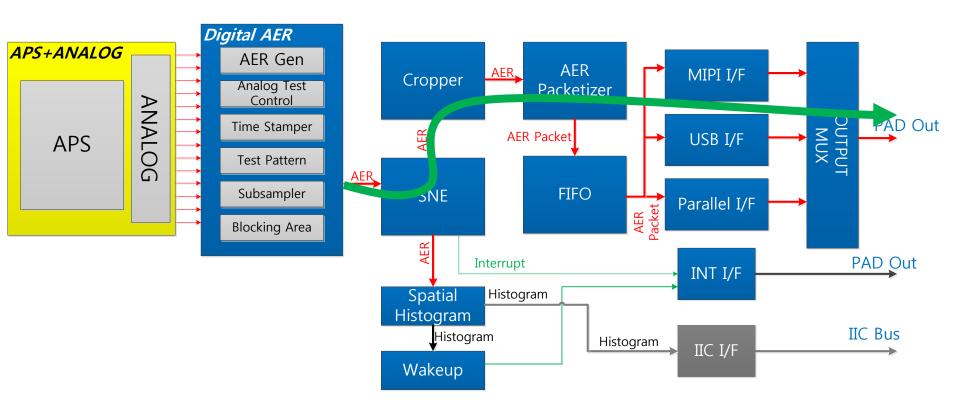
640x480 Image Plane

# **Reducing Power: Statistics for Dynamic Decisions**

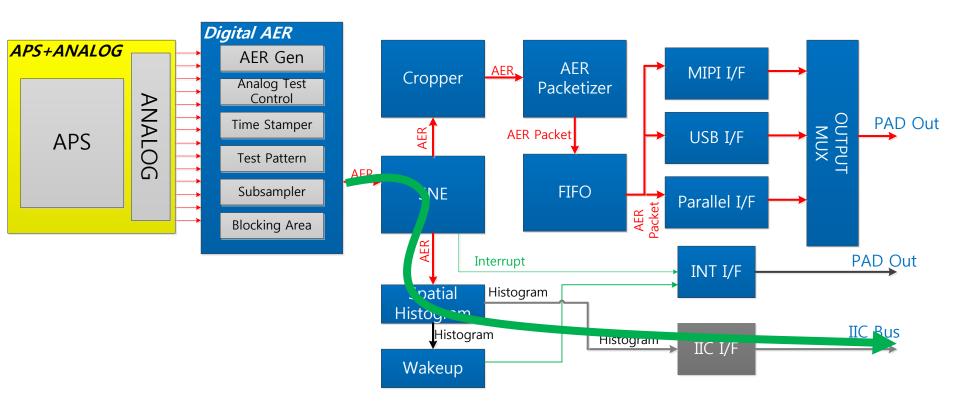


**Spatial Histogram Data** 

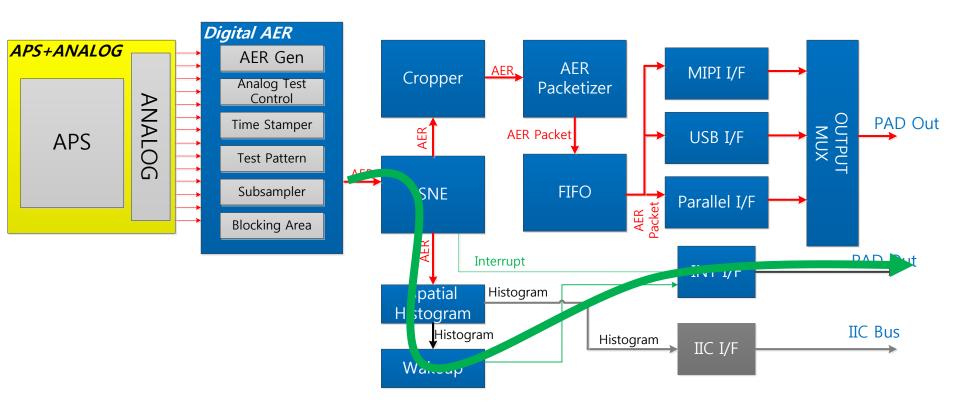
## Reducing Power: Blocking, Subsampling



## **Reducing Power: Statistics Collection**



## **Reducing Power: Wakeup**



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# **Good Event Quality: Objective**

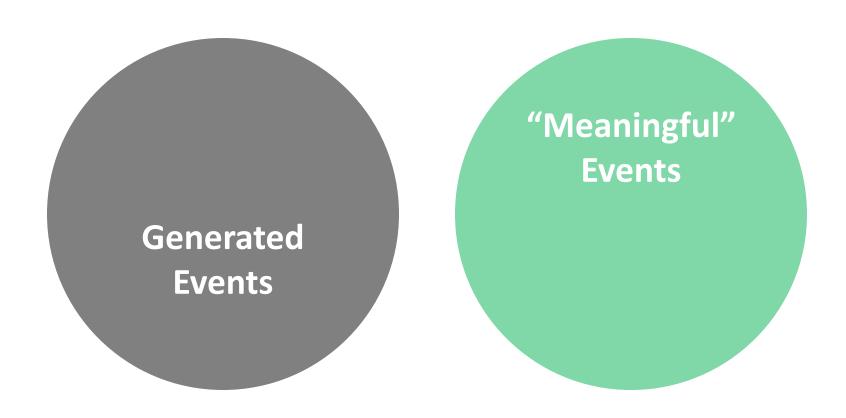




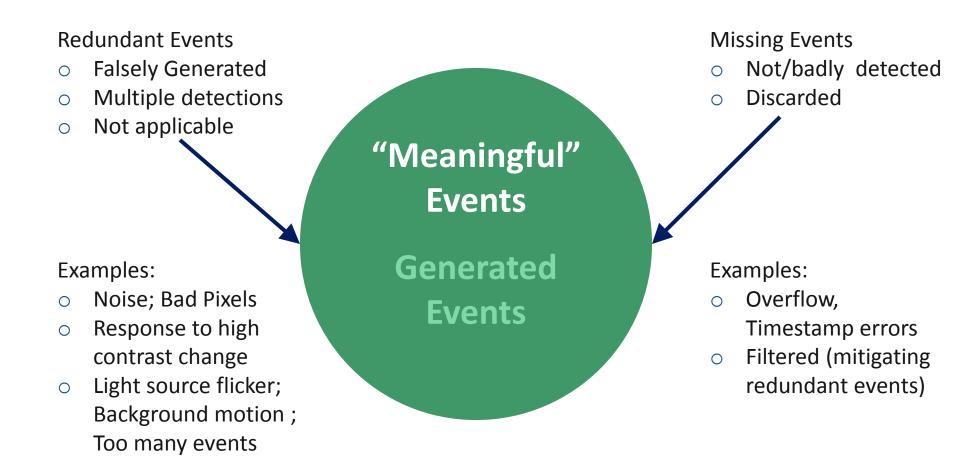
Clean and perfect edge map

→ Obtained by subtracting frames on a High Frame-Rate CIS camera

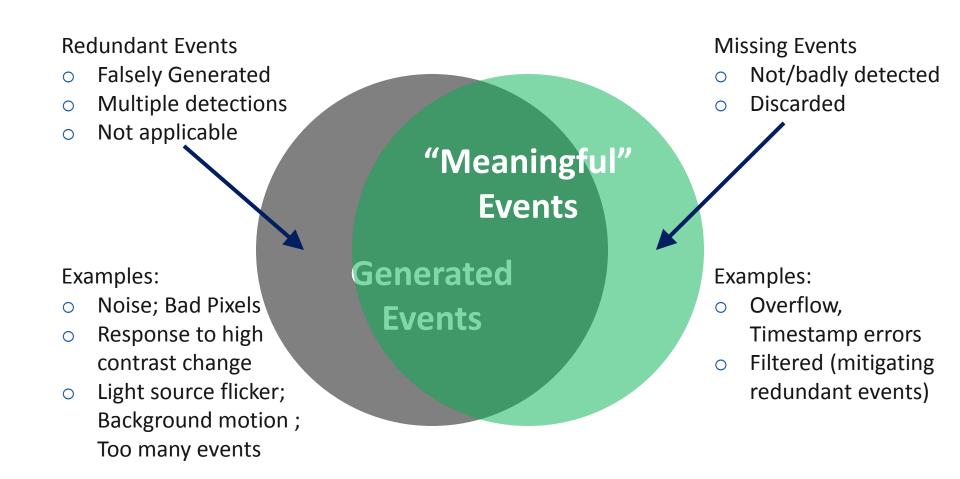
# **Good Event Quality**



#### **Good Event Quality**



#### **Good Event Quality**

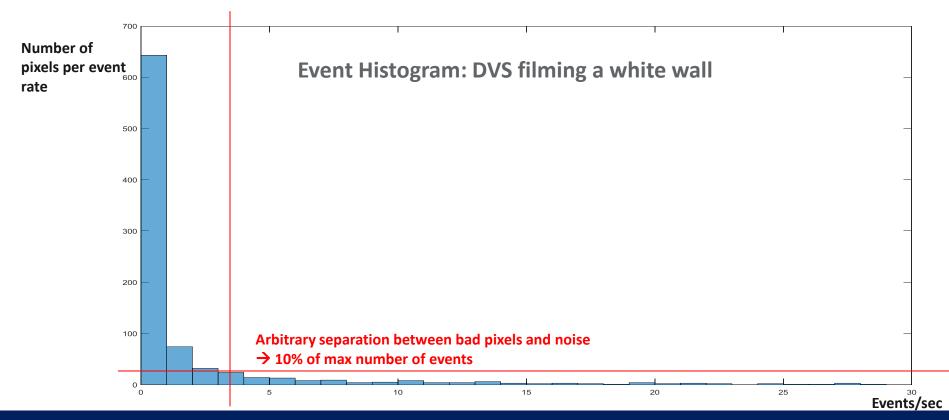


#### Redundant Events: Bad Pixels; Noise

#### **Basic model:**

- O Bad Pixel: Specific Pixels that generate events at high frequency (regardless of the scene)
- Noise: Random pixels that generate events at low frequency (regardless of the scene)

#### **Actual behavior:**



## Redundant Events: Bad Pixels; Noise

#### **Bad Pixel Suppression Example:**

# Before chain

#### After chain



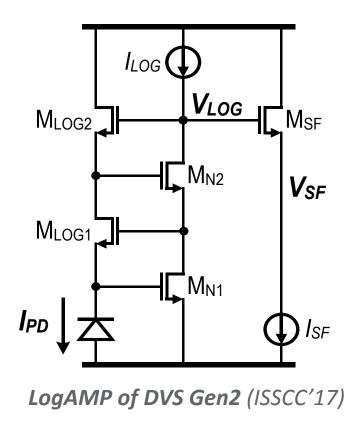
# Redundant Events: Bad Pixels; Noise

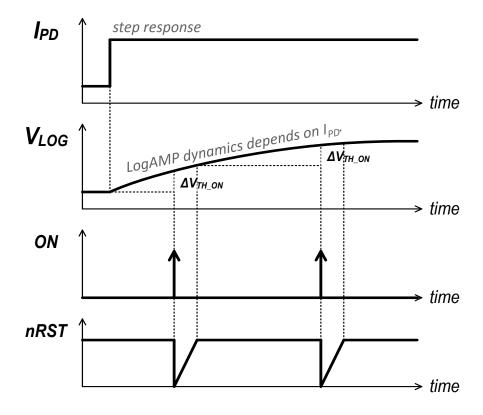
#### **Noise Suppression Example:**



#### **Redundant Events: Multiple detections**

- Overall pixel BW (speed) is limited by LogAMP BW
- LogAMP BW is mainly affected by 1) Its structure; 2) The amount of photocurrent
- Redundant events generated at low light (I<sub>PD</sub>) on @ large contrast change



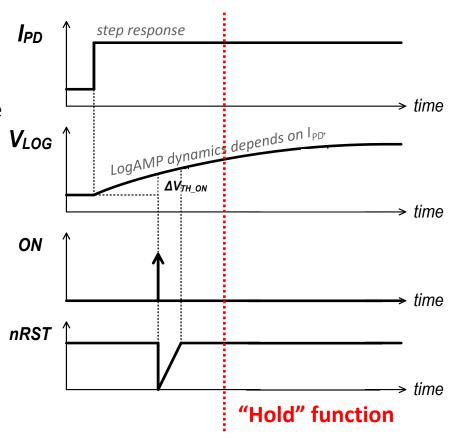


#### **Redundant Events: Multiple detections**

- Overall pixel BW (speed) is limited by LogAMP BW
- LogAMP BW is mainly affected by 1) Its structure; 2) The amount of photocurrent
- Redundant events generated at low light (IPD) on @ large contrast change

#### **Solutions:**

- Structure:
   Increase ~x5-x10 LogAMP BW by new structure
- Limit photocurrent:
   Introduce "HOLD" signal to pixel



# **Redundant Events: Light Source Flicker**

#### Light Source Flicker:

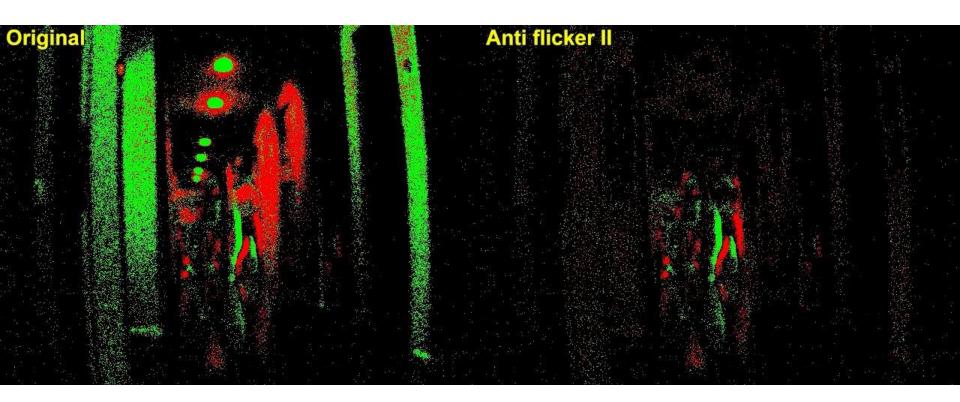
Events that are not generated by motion but by flickering lights (with different frequencies)

#### O Note:

This has to be differentiated from periodic motion (for example a waving hand)

# **Redundant Events: Light Source Flicker**

#### **Flicker Suppression Example:**

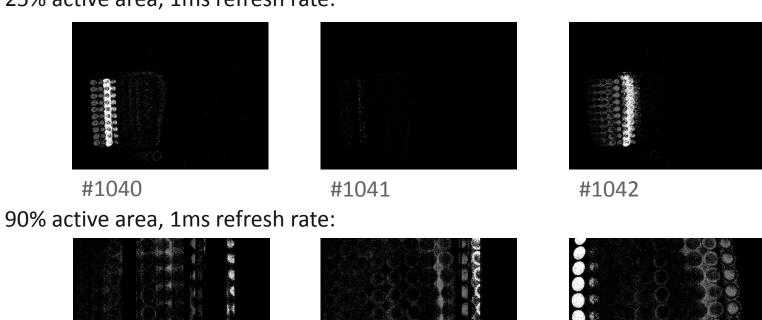


#### Missing Events: Overflow, Timestamp Errors

#### Overflow:

Number of events describing the scene change, exceeds the circuit maximal throughput.

25% active area, 1ms refresh rate:



#109

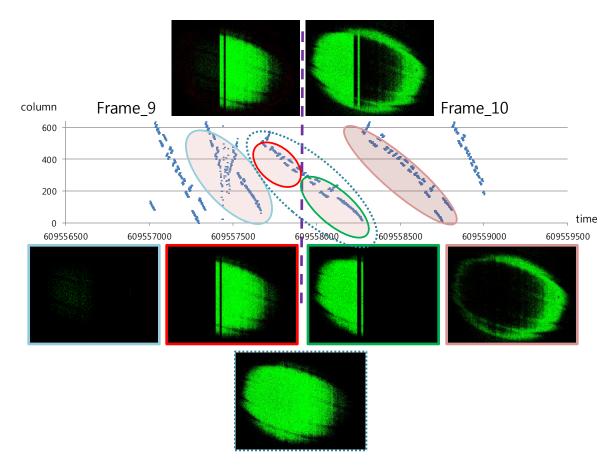
#110

#110

## Missing Events: Overflow, Timestamp Errors

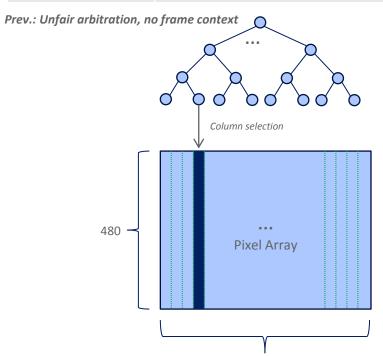
#### Timestamp Errors:

Events grouped according to incorrect timestamp

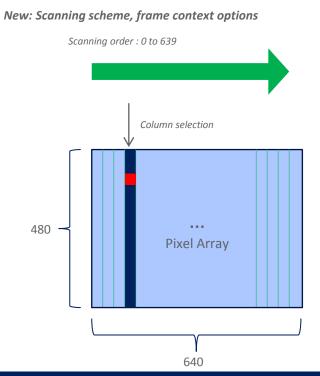


#### **Solution: Pixel Readout Revision**

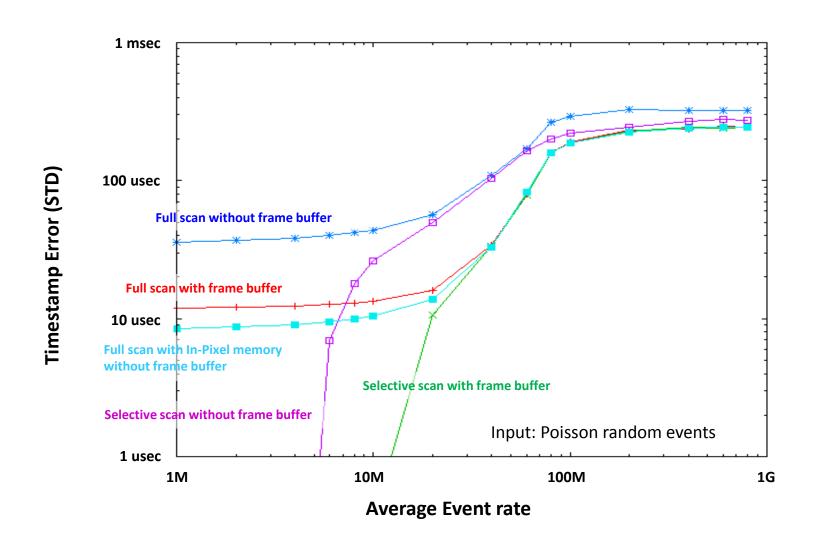
Readout controls	Gen1 & Gen2	Gen3
Column selection	Unfair arbitration scheme	Scanning scheme
In-pixel memory	Free running (no event hold)	Free running (no event memory)
		Global hold (all pixels in pixel array)
	Pixels with an event in a column	Pixels with an event in a column
Pixel reset	-	All pixels in a column
	-	Global reset (all pixels in pixel array)



640



## **Pixel Readout: Timestamp Error Comparison**

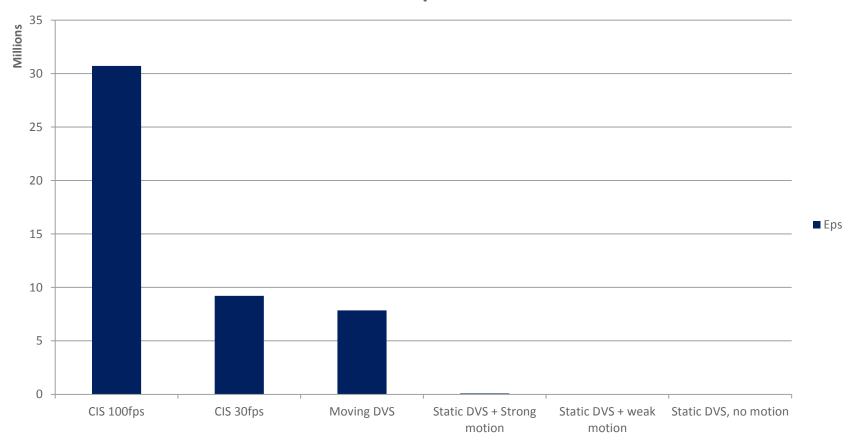


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## Data Throughput: DVS Low Event Rate Example

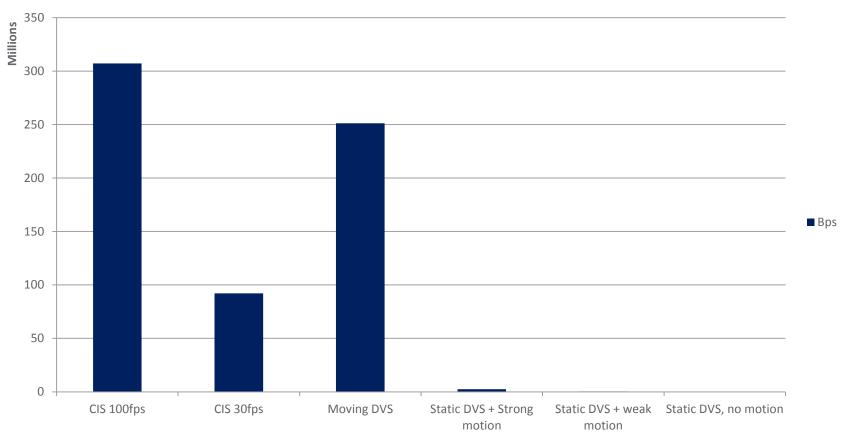




Less Events → Easier to process

# Data Bandwidth @ 32 bit/event Encoding





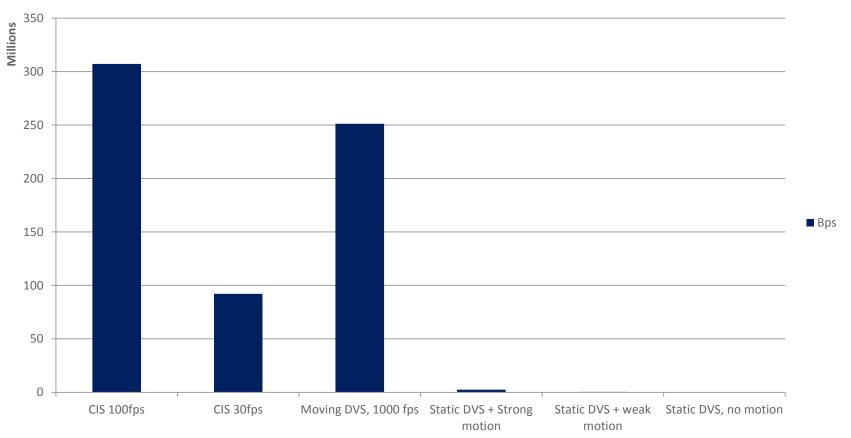
DVS AER 32bit per event

## **Group Address Event Representation (GAER)**

GAER (~64-4 bits/event – content dependent) AER (32 bits/event) Address Event Representation (TS, X, Y, event) Group AER (TS, X, G, group\_event) P: packet encoding (2bit) P: packet encoding (10bit group, 12bit per col) TS: timestamp (10bit) TS: timestamp (10bit) X : column address :  $0 \sim 639$  (10bit) X: column address: 1 ~ 640 (10bit) Y: row address: 0 ~ 479 (9bit) G: group address: 1 ~ 60 (6bit) event: 1-bit. on/off group event: a bundle of 8 events. 16-bits on evnet: 8-bits 640 off event: 8-bits (0,0)event group\_event 480

# Data throughput: AER 32 bit/event

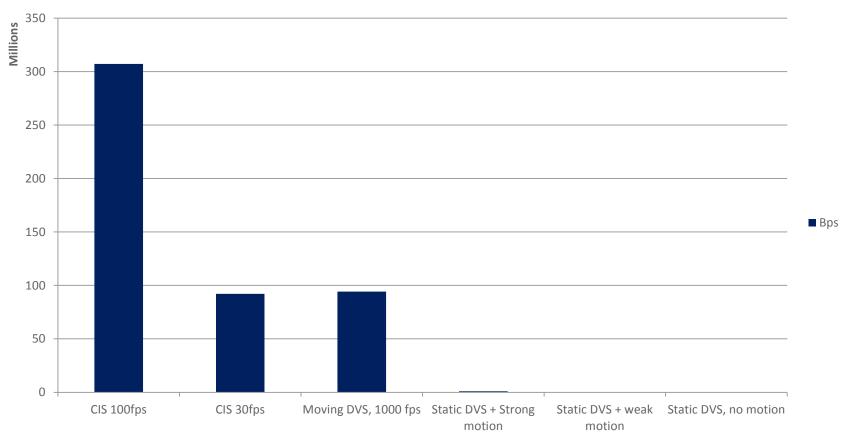




DVS AER 32bit per event

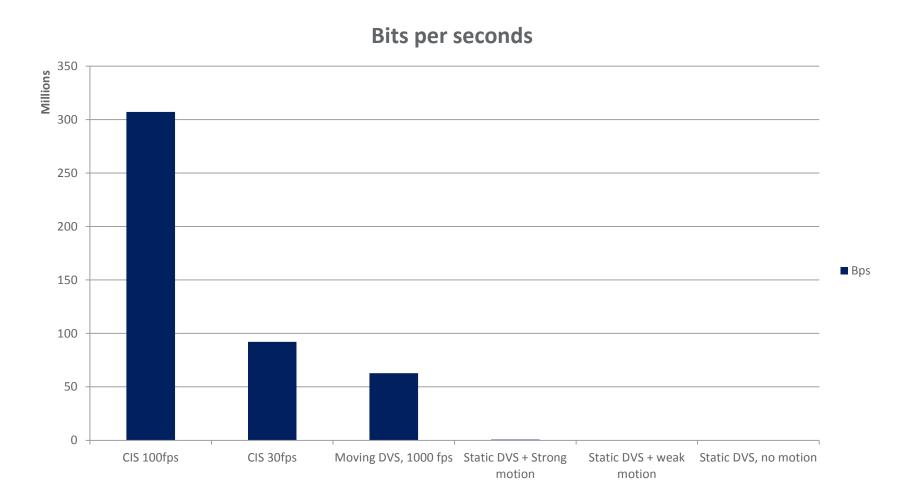
# Data throughput: GAER ~12 bit / event





DVS GAER 12bit per event (average)

# Data throughput: Improved GAER ~8 bit / event



DVS GAER with offset based column 8 bit per event (average)

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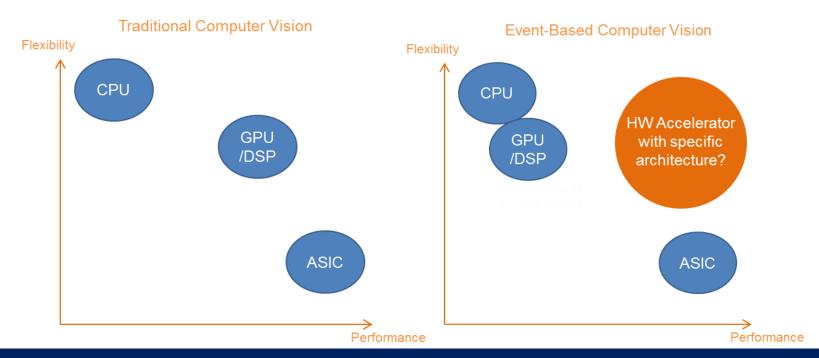
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# **Event Processing Acceleration**

GPU/DSP are not optimized for event-based computer vision:

	GPU/DSP	Requirements for Event Processing
Optimized for	High arithmetic density and high throughput	Low latency
Memory access	Privilege coalesced data	Optimized for random access

Considering HW accelerator/processor with a DVS-specific architecture



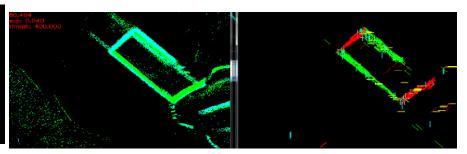
# **Concept: Less but More Informative Events**

- Programmable feature
- A feature event is sent by the sensor when the feature appears strongly
- For example: direction detection (can be used to produce Histogram of Gradients in the Host for *human detection*)

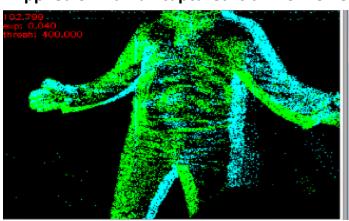
#### Horizontal (yellow) and vertical (cyan):

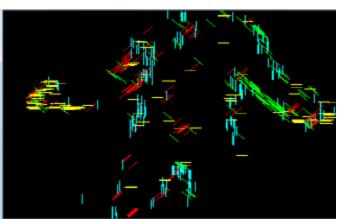
# 10.718 (mosh) 400.000

#### Slash (red) and Backslash (green):



#### Applied on Human captured is a DVS movie:





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# **Summary: Market Driven Requirements**

Requirements	Samsung Early Prototypes	Samsung DVS Product Roadmap (2017,2018)
Low Cost	Large Pixel No standard for Quality / Die sorting	Similar size to 16-8MP mobile camera
Minimal Module Size	Large, due to large Pixel -> Large optical format	Smaller, Optical size reduced to 1/3" (VGA)
Ultra Low Power	Low power	Lower power
Minimal Optical Format	Large, due to large Pixel	Reduced to 1/3" (VGA)
Good Event Quality	Redundant events (especially at low light) Motion artifacts, Timing accuracy Noise, Flicker	Improved pixel circuit. On chip Bad Pixel, Noise and flicker suppression. External Triggered Scan, Global reset & hold capable
Low Data Rate	Scene dependent Might exceed CIS typical throughput	Compressed format in the bounds of slow CIS typical throughput
Edge device vision processing	Not available	Considering low level features

## **Thank You!**